Summary
The TI WiLink WL18xx MCP driver does not limit the number of information elements (IEs) of type XCC_EXT_1_IE_ID or XCC_EXT_2_IE_ID that can be parsed in a management frame. Using a specially crafted frame, a buffer overflow can be triggered that can potentially lead to remote code execution.

Vulnerability
TI PSIRT ID
TI-PSIRT-2022-120160

CVE ID:
CVE-2023-29468

CVSS Score
The CVSS base score for this issue can range from 8.8 to 9.6. The higher base score reflects a Confidentiality and Integrity impact of High. However, some systems can have a Confidentiality or Integrity Impact of Low depending on the characteristics of the host processor executing the WL18xx MCP driver and whether the disclosure or modification of the memory that can be accessed represents a direct or serious loss.

CVSS vector

Affected Products
• WILINK8-WIFI-MCP8 version 8.5_SP3 and earlier

Potentially Impacted Features
An attacker within wireless range of a potentially vulnerable device can gain the ability to overwrite memory of the host processor executing the MCP driver.

Suggested Mitigations
In MCP8.5_SP3\WiLink\UWD\src\Services\mlmeParser.c, include the following code starting at line 720:

```c
if( rsnIeIdx >= 3 )
{
    TRACE(pHandle->hReport, REPORT_SEVERITY_ERROR, "MLME_PARSER: Number of RSN IEs exceeds 3\n");
    return TI_NOK;
}
```

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